



NOTES

1. LEAD WIDTH AND LEAD THICKNESS EXCLUSIVE OF SOLDER PLATE
2. PACKAGE OUTLINE EXCLUSIVE OF MOLD FLASHES AND BURR DIMENSIONS
3. ALLOWABLE MOLD FLASH IS 5 MILS PER SIDE.
4. LEAD COPPLANARITY IS 0.003 INCH MAX.

SYMBOL	DIMENSION IN MM			DIMENSION IN INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A			1.20			.043
A1	0.05		0.15	.002		.006
A2	0.80	0.90	1.05	.031	.035	.041
L	0.46	0.61	0.76	.018	.024	.030
D	6.40	6.50	6.60	.252	.256	.260
E	6.30	6.40	6.50	.248	.252	.256
E1	4.30	4.40	4.50	.169	.173	.177
R	0.09			.004		
R1	0.09			.004		
b	0.19		0.30	.007		.012
b1	0.19	0.22	0.25	.007	.009	.010
c	0.09		0.20	.004		.008
c1	0.09		0.16	.004		.006
L1		1.0 REF.			.039 REF.	
e		0.65 BSC.			.026 BSC.	
01	0		8	0		8
02		12 REF.			12 REF.	
03		12 REF.			12 REF.	
N			20			
REF		JEDEC MO-153 VARIATION AC				



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TITLE:
POD for 20LD TSSOP (173 MIL),
0.65MM PITCH

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